



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Board Level Cooling – Surface Mount 5731



BOARD LEVEL COOLING – Surface Mount 5731

Surface Mount 5731 is a series of surface mount board level heat sinks designed to cool D-Pak and TO-252 devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
573100D00000G	D-Pak, TO-252
573100D00010G	D-Pak, TO-252



HEAT SINK DETAILS

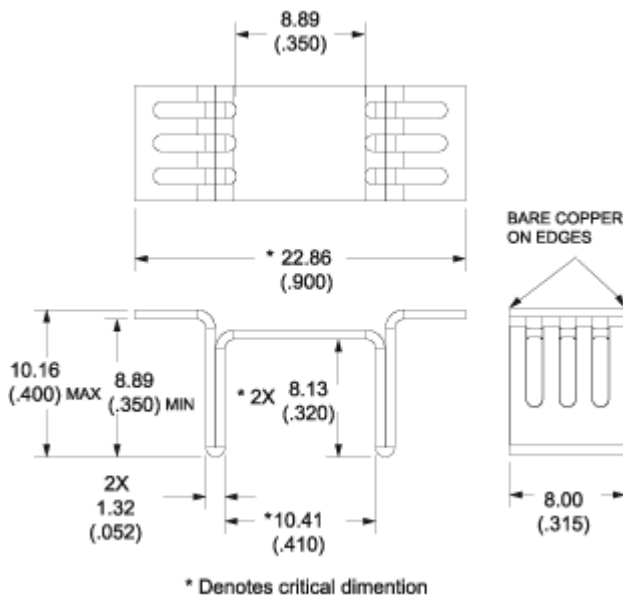
Property	Details
Material	Aluminum
Finish	Tin Plated
Device Attachment Options	-
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	8
Heat Sink Length (mm)	10.16
Heat Sink Height (mm)	22.86
Heat Sink Mounting Direction	Horizontal

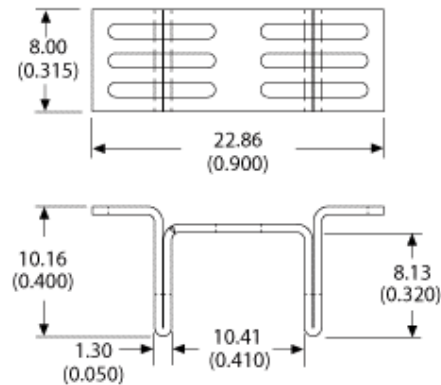
MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

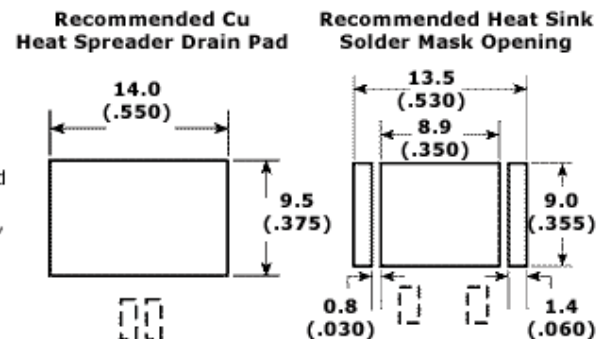
Part Number: 573100D00000G



Part Number: 573100D00010G



Note: The thickness of the drain pad is variable depending on the amount of heat generated by the SMT device, design, limitations and process. This is the exposed printed circuit.



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